

AK-460 THERMAL COMPOUND

Introduction

Pro-Grade Silicone Technology Evolution leads to Outstanding Thermal Performance

Pro-grade Silicone technology evolution thermal compound delivers a stable and reliable thermal performance. Minimised resistance and maximised efficiency truly enables you to get more from your cooler. RoHS compliant.

Features

- Outstanding performance of heat transfer between CPU and heatsink
- Low thermal resistance for heat transfer, $0.16\text{cm}^2\text{C/W}$ @60 μm BLT
- Maximum thermal conductivity, 3.3W/mK
- Electrically non-conductive
- Low bleed under high pressure
- Multi-language instructions included

Specification

Colour	Grey
Viscosity	102K cPs
Thermal conductivity	3.3 W/mK
Operating temperature	$-45^\circ\text{C} \sim 200^\circ\text{C}$
Operating Range	$0.16\text{cm}^2\text{C/W}$ @60 μm BLT
Volume	3.5g
Product code	AK-460

Includes

- Spreader card

Miscellaneous

Installation

1. Before applying the thermal compound, please make sure the top surface of the CPU die or heat spreader is perfectly clean. If the die has any residue of old thermal compound present, clean off with Isopropyl or AKASA Timclean.
2. Place a small amount of AK-460 on the surface of the die and carefully spread evenly using the spreader card included. A thin film is ideal; extra thermal compound will not improve performance.
3. Now you are ready to install your CPU cooler.

